



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL32A226KPJNFNE

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 22 µF, 10V, ±10%, X5R, 1210

A. Samsung Part Number

<u>CL</u> <u>32</u> <u>A</u> <u>226</u> <u>K</u> <u>P</u> <u>J</u> <u>N</u> <u>F</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor										
2	Size	1210	(inch c	ode)	L:	3.2	± 0.3	mm	W:	2.5	± 0.2	mm
3	Dielectric	X5R				8	Inner el	lectrode		Ni		
4	Capacitance	22	μF				Termin	ation		Cu		
5	Capacitance	±10	%				Plating			Sn 10	00%	(Pb Free)
	tolerance					9	Produc	t		Produ	uct for P	OWER application
6	Rated Voltage	10	V			10	Special			Rese	rved for	future use
7	Thickness	2.5	± 0.2	mm		11)	Packag	ing		Embo	ssed T	ype, 7" reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	120Hz ±20% 0.5±0.1Vrms						
Tan δ (DF)	0.1 max.							
Insulation	10,000Mohm or 100Mohm⋅µF	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	250% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	X5R							
Characterisitcs	(From -55℃ to 85℃, Capacitance change should be within ±15%)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating: 80~120°C for 10~30sec.)						
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	Tan δ, IR : initial spec.							

	Performance	Test condition
Vibration Test	Capacitance change: within ±5%	Amplitude: 1.5mm
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)
		2hours × 3 direction (x, y, z)
Moisture	Capacitance change: within ±12.5%	With rated voltage
Resistance	Tan δ: 0.125 max	40±2℃, 90~95%RH, 500+12/-0hrs
	IR: 12.5MΩ·μF or Over	
High Temperature	Capacitance change: within ±12.5%	With 150% of the rated voltage
Resistance	Tan δ: 0.125 max	Max. operating temperature
	IR: 25MΩ·μF or Over	
		1000+48/-0hrs
Temperature	Capacitance change: within ±7.5%	1 cycle condition
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25 °C
		→ Max. operating temperature → 25°C
		5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.